REPLACEMENT SHEET

Title: Integration of Annealing Capability Into Metal Deposition or CMP Tool

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Application No.: 10/810,735 Docket No. 42P6934D

WAFERS HAVING METAL LAYERS DEPOSITED THEREON

METAL LAYER
WAFER

METAL LAYER

WAFER

FIG. 7

WAFERS HAVING METAL LAYERS THAT HAVE BEEN POLISHED

POLISHED METAL LAYER

WAFER

POLISHED METAL LAYER

WAFER

FIG. 8